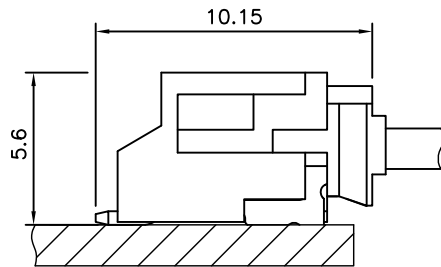
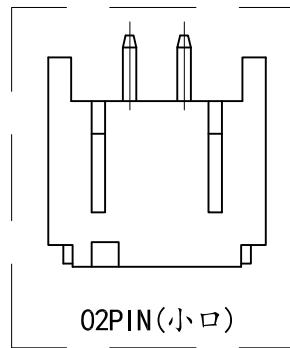
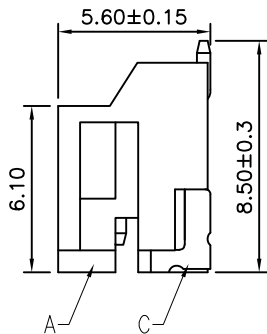
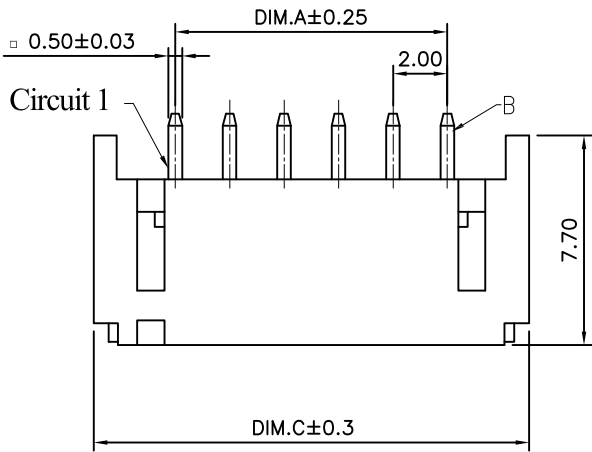
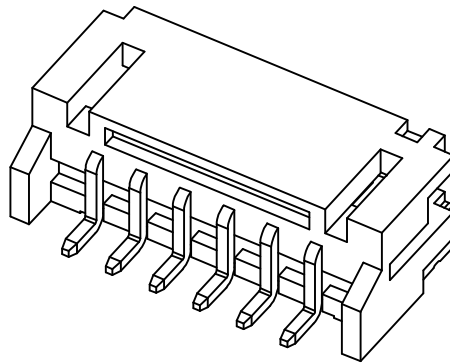
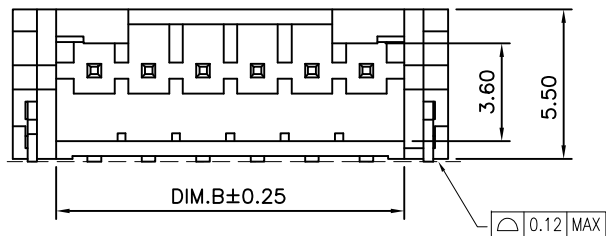


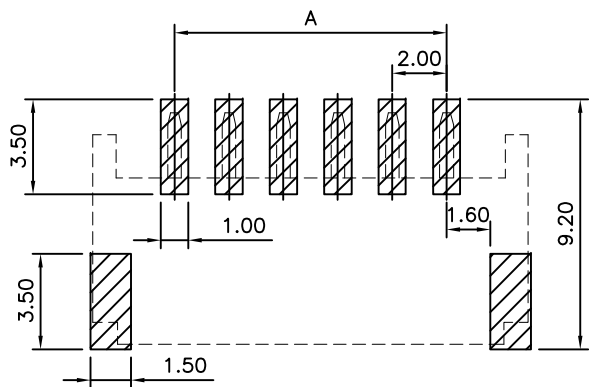
REV.	LOCAS.	DESCRIPTION	DATE	DRAWN
01	NEW	BATCH PRODUCTION INITIAL RELEASE.	2024.09.05	谢青平



Assembly Layout



Specifications  
 Current Rating:2Amp  
 Insulation Resistance:1000MΩ Min.  
 Dielectric Withstanding Voltage:1000V AC DC  
 Rated Voltage: 250V AC DC  
 Contact Resistance:20mΩ Max  
 Operating Temperature:-25°C to +105°C  
 Materials  
 Contact Material:Brass  
 Insulation Material UL94V-0 LCP  
 All materials must meet GREENCONN hazardous substances control standards



SUGGESTED PCB LAYOUT

### Ordering Information

G WFD117 - XX XX A 001 C X B X  
 No. of Pins per Row 02~16      Standard Plating 01=Tin      Color 5=Beige      Standard Packing D=Tape&Reel

No. of pin/Row	Dimensions(mm)		
	A	B	C
02	2.00	4.75	8.00
03	4.00	6.75	10.00
04	6.00	8.75	12.00
05	8.00	10.75	14.00
06	10.00	12.75	16.00
07	12.00	14.75	18.00
08	14.00	16.75	20.00
09	16.00	18.75	22.00
10	18.00	20.75	24.00
11	20.00	22.75	26.00
12	22.00	24.75	28.00
13	24.00	26.75	30.00
14	26.00	28.75	32.00
15	28.00	30.75	34.00
16	30.00	32.75	36.00



3RD.ANG PROJ.  
  
 PAGE. 1/1

GENERAL TOLERANCE	
X.*±5.0*	X.±0.50
.X*±3.0*	.X±0.30
.XX*±2.0*	.XX±0.25
.XXX*±1.0*	.XXX±/

DESIGNED: 谢青平

DATE: 2024.09.05

DWG. NO.

GWFD117-A001CB

CHECKED:

DATE:

PART NO.

GWFD117-XXXXA001CXBX

APPROVED:

DATE:

TITLE.

2.0mm PITCH 90°  
 WAFER SMT TYPE

REV.	UNIT.	SCALE.
01	mm	1:1